

### 2 Photodiodes in One Chip for Spacially Resolved Light Detection

The PR5001 is a dual-element Si photodiode moulded into a small plastic leadless optical package. Produced as one chip, the photodiodes offer a very good symmetry, low dark current and high sensitivity.

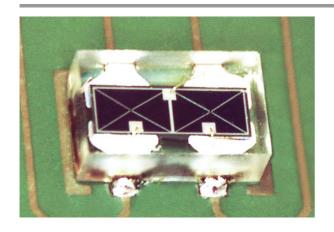
Apart from the standard version **PR5001**, the **PR5001-ARC** features an antireflective layer, smoothing the spectral sensitivity and providing a high good matching from part to part.

#### **FEATURES**

- Low dark current
- Low capacitance
- Good matching between photodiodes

#### **TYPICAL APPLICATIONS**

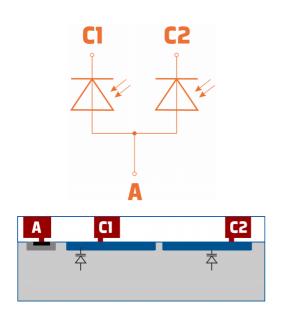
- Laser beam alignment
- Opto encoders
- Position detection
- Differential light measurement



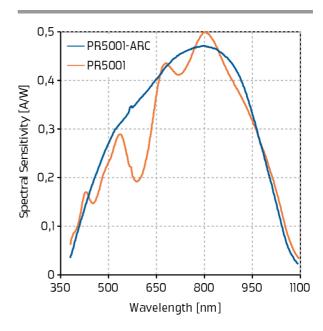
#### **KEY CHARACTERISTICS**

Parameter	Тур	Unit
package size	2,9 x 1,8 x 0,9	mm³
photodiode size	2 x 0,78	mm²
peak wavelength (-ARC)	800	nm
dark current @ 40°C / Vr = 1 V	14	рА
capacitance @ Vr = 2 V	40	рF

#### **CIRCUIT**



#### **SPECTRAL SENSITIVITY**





## **Electrical and optical Characteristics**

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Min	Max	Units
V <sub>C-A</sub>	V(A) - V(C1, C2)	-0,3	35	V
T <sub>S</sub>	storage temperature	-40	85	°C
T <sub>peak</sub>	soldering peak temperature		260	°C
P <sub>tot</sub>	total power dissipation		100	mW

#### **ELECTRICAL CHARACTERISTICS**

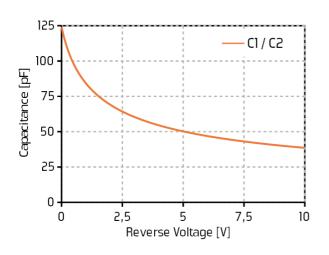
Ta = 27°C, unless otherwise noted.

Symbol	Parameter		Conditions	Min	Тур	Max	Units
T <sub>A</sub>	operating ambient temperature			-40		85	°C
V <sub>r (A-C)</sub>	reverse voltage $V(A) - V(C)$					28	V
$A_{PD}$	active area (geometrical)	C1, C2	width height inactive area (pads) effective active area		1145 738 0,064 0,781		hm hm mm <sub>s</sub>
I <sub>d</sub>	dark current	C1, C2	$V_r = 10V$		10		рА
$\Delta I_d/\Delta T$	temperature coefficient of dark current	C1, C2	$V_r = 10V$		10		%/K
$\lambda_{peak}$	peak sensitivity wavelength	C1, C2	PR5001-ARC		800		nm
S <sub>peak</sub>	peak sensitivity	C1, C2	PR5001-ARC		0,47		A/W
C <sub>j0</sub>	zero-bias junction capacitance	C1, C2	$V_r = 0V$ , $f = 1 MHz$		125		рF
Cj	biased junction capacitance	C1, C2	$V_r = 10V, f = 1 MHz$		38		рF

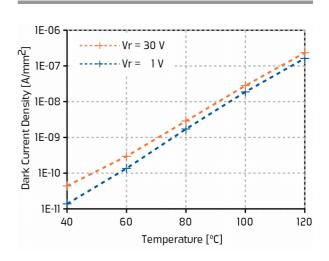


## **Electrical and Optical Characteristics**

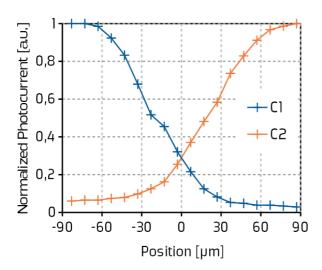
#### **CAPACITANCE VS. REVERSE VOLTAGE**



#### **DARK CURRENT VS. TEMPERATURE**



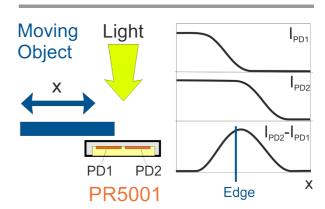
#### **CHANNEL SEPARATION**



The crosstalk between both photodiodes C1/C2 was measured with a wavelength of 660 nm. The crossover of a light spot with a diameter of 100  $\mu$ m from one photodiode to the other has been resolved with increments of 10  $\mu$ m. The photocurrent was measured with an applied reverse voltage of 4 V.

Considering a beam diameter of 100  $\mu$ m and a gap between both photodiodes of 50  $\mu$ m, the observed behaviour is consistent with almost sharp channel separation.

#### **EDGE DETECTOR**

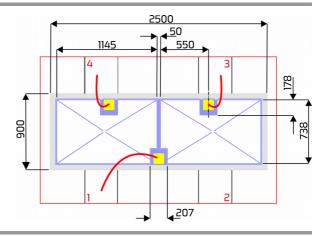




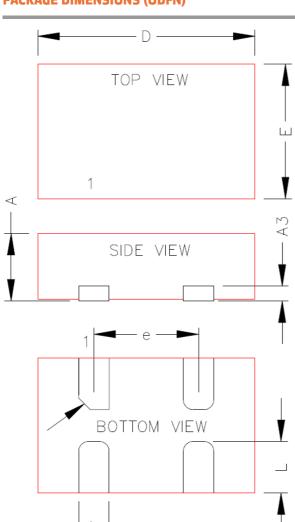
## Package Information

#### **LAYOUT AND PIN CONFIGURATION**

Pin No.	Pin Name	<b>PIN Function Description</b>
1	А	Common Anode
2		Not connected
3	C2	Cathode photo diode 2
4	C1	Cathode photo diode 1



#### **PACKAGE DIMENSIONS (ODFN)**



Min	Тур	Max	Unit
0,85	0,9	0,95	mm
	0,20 REF.		mm
0,35	0,4	0,45	mm
2,8	2,9	3	mm
1,7	1,8	1,9	mm
	1,4 BSC*		mm
0,6	0,7	0,8	mm
	0,85 0,35 2,8 1,7	0,85 0,9 0,20 REF. 0,35 0,4 2,8 2,9 1,7 1,8 1,4 BSC*	0,85 0,9 0,95  0,20 REF.  0,35 0,4 0,45  2,8 2,9 3  1,7 1,8 1,9  1,4 BSC*

<sup>\*</sup> Basic Spacing Between Centers



### Package Information

#### **SOLDERING INFORMATION**

A lead-free solder profile with a peak temperature of 260°C or less, according to J-STD-020 should be followed.

Parts should be handled in accordance with the moisture sensitivity level as indicated on the moisture barrier bag, but at least to MSL 3. Any parts without or with unsealed moisture barrier bag must be dry-baked according to JEDEC guidelines before soldering. Manual soldering must be done with utmost care. Direct infrared heating should be avoided; pure convection heating is recommended.

#### **TAPE & REEL**

Reel diameter: 7" (178 mm)

Tape width: 8 mm

Quantity per reel: 3,000

Packaging: moisture barrier bag

Orientation of ICs in tape: Pins 3 and 4 towards

sprocket holes

#### **BARE DIES**

PR5010 is available as bare dies on request on tested and sawn wafers or in wafflepack. Please contact us for minimum order quantities and delivery times.



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